

## Features

- Supply Voltage 5V (Typically)
- Very Low Power Consumption: 150 mW (Typically) for -1 dBm Output Level
- Very Good Sideband Suppression by Means of Duty Cycle Regeneration of the LO Input Signal
- Phase Control Loop for Precise 90° Phase Shifting
- Power-down Mode
- Low LO Input Level: -10 dBm (Typically)
- 50-Ω Single-ended LO and RF Port
- LO Frequency from 100 MHz to 1 GHz
- SO16 Package

## Benefits

- No External Components Required for Phase Shifting
- Adjustment Free, Hence Saves Manufacturing Time
- Only Three External Components Necessary, this Results in Cost and Board Space Saving

Electrostatic sensitive device.

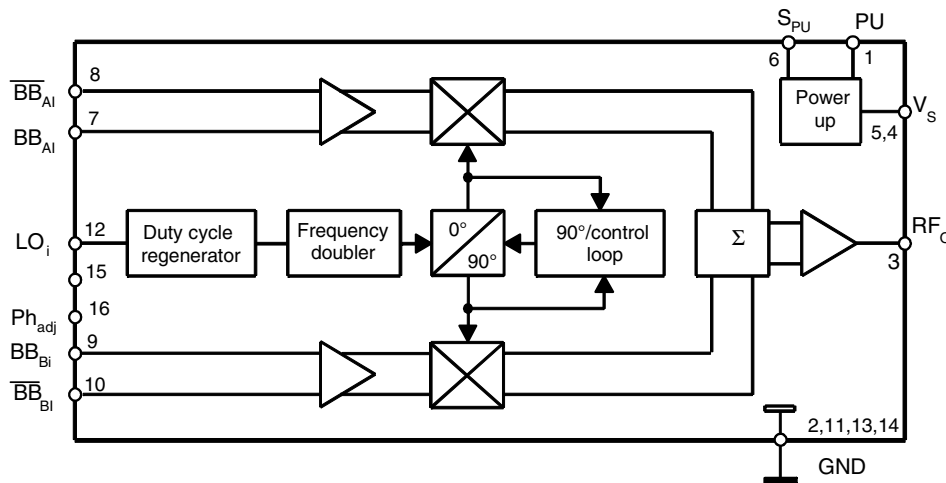
Observe precautions for handling.



## 1. Description

The U2790B is a 1000-MHz quadrature modulator using Atmel®'s advanced UHF process. It features a frequency range from 100 MHz up to 1000 MHz, low current consumption, and single-ended RF and LO ports. Adjustment-free application makes the direct converter suitable for all digital radio systems up to 1000 MHz, e.g., GSM, ADC, JDC.

Figure 1-1. Block Diagram



# 1000-MHz Quadrature Modulator

## U2790B

## 2. Pin Configuration

Figure 2-1. Pinning SO16

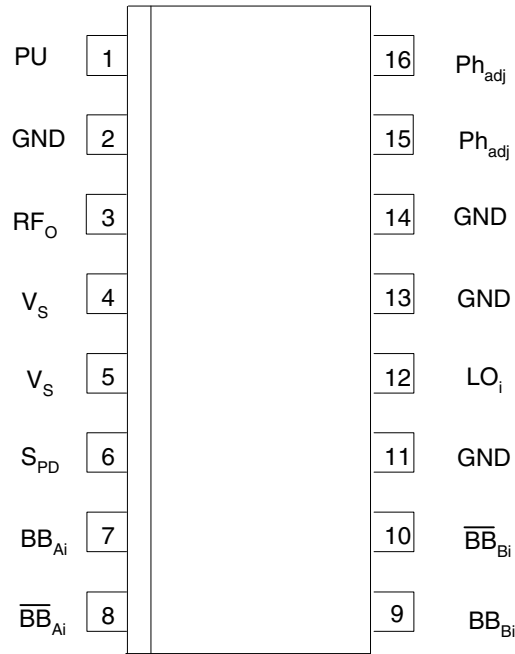


Table 2-1. Pin Description

Pin	Symbol	Function
1	PU	Power-up input
2, 11, 13, 14	GND	Ground
3	RF <sub>O</sub>	RF output
4, 5	V <sub>S</sub>	Supply voltage
6	S <sub>PU</sub>	Settling time power-up
7	BB <sub>Ai</sub>	Baseband input A
8	$\overline{\text{BB}}_{\text{Ai}}$	Baseband input A inverse
9	BB <sub>Bi</sub>	Baseband input B
10	$\overline{\text{BB}}_{\text{Bi}}$	Baseband input B inverse
12	LO <sub>i</sub>	LO input
15, 16	Ph <sub>adj</sub>	Phase adjustment (not necessary for regular applications)

## 3. Absolute Maximum Ratings

Parameters	Symbol	Value	Unit
Supply voltage	$V_S$	6	V
Input voltage	$V_i$	0 to $V_S$	V
Junction temperature	$T_j$	125	°C
Storage temperature range	$T_{Stg}$	-55 to +125	°C

## 4. Operating Range

Parameters	Symbol	Value	Unit
Supply voltage range	$V_S$	4.5 to 5.5	V
Ambient temperature range	$T_{amb}$	-40 to +85	°C

## 5. Thermal Resistance

Parameters	Symbol	Value	Unit
Junction ambient SO16	$R_{thJA}$	110	K/W

## 6. Electrical Characteristics

Test conditions (unless otherwise specified):  $V_S = 5V$ ,  $T_{amb} = 25^\circ C$ , referred to test circuit, system impedance  $Z_O = 50\Omega$ ,  $f_{LO} = 900$  MHz,  $P_{LO} = -10$  dBm,  $V_{BBi} = 1 V_{pp}$  differential.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Typ.	Max.	Unit	Type*
1.1	Supply voltage range		4, 5	$V_S$	4.5		5.5	V	A
1.2	Supply current		4, 5	$I_S$	24	30	37	mA	A
<b>2</b>	<b>Baseband Inputs</b>								
2.1	Input-voltage range (differential)		7-8, 9-10	$V_{BBi}$		1000	1500	$mV_{pp}$	D
2.2	Input impedance (single ended)			$Z_{BBi}$		3.2		$k\Omega$	D
2.3	Input-frequency range <sup>(5)</sup>			$f_{BBi}$	0		250	MHz	D
2.4	Internal bias voltage			$V_{BBb}$	2.35	2.5	2.65	V	A
2.5	Temperature coefficient			$TC_{BB}$		0.1	<1	$mV/^\circ C$	D

\* ) Type means: A = 100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

- Notes:
1. The required LO level is a function of the LO frequency.
  2. In reference to an RF output level  $\leq -1$  dBm and I/Q input level of  $400 mV_{pp}$  differential.
  3. Sideband suppression is tested without connection at pins 15 and 16. For higher requirements a potentiometer can be connected at these pins.
  4. For  $T_{amb} = -30^\circ C$  to  $+85^\circ C$  and  $V_S = 4.5V$  to  $5.5V$ .
  5. By low impedance signal source.

## 6. Electrical Characteristics (Continued)

Test conditions (unless otherwise specified):  $V_S = 5V$ ,  $T_{amb} = 25^\circ C$ , referred to test circuit, system impedance  $Z_0 = 50\Omega$ ,  $f_{LO} = 900\text{ MHz}$ ,  $P_{LO} = -10\text{ dBm}$ ,  $V_{BBI} = 1\text{ V}_{pp}$  differential.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Typ.	Max.	Unit	Type*
<b>3</b>	<b>LO Input</b>								
3.1	Frequency range		12	$f_{LOi}$	50		1000	MHz	D
3.2	Input level <sup>(1)</sup>			$P_{LOi}$	-12	-10	-5	dBm	D
3.3	Input impedance			$Z_{ILO}$		50		$\Omega$	D
3.4	Voltage standing wave ratio			$VSWR_{LO}$		1.4	2		D
3.5	Duty cycle range			$DCR_{LO}$	0.4		0.6		D
<b>4</b>	<b>RF Output</b>								
4.1	Output level		3	$P_{RFo}$	-5	-1	+2	dBm	B
4.2	LO suppression <sup>(2)</sup>	$f_{LO} = 900\text{ MHz}$ $f_{LO} = 150\text{ MHz}$		$LO_{RFo}$	30 32	35 35		dB	B
4.3	Sideband suppression <sup>(2, 3)</sup>	$f_{LO} = 900\text{ MHz}$ $f_{LO} = 150\text{ MHz}$		$SBS_{RFo}$	35 30	40 35		dB	B
4.4	Phase error <sup>(4)</sup>			$P_e$		<1		deg.	D
4.5	Amplitude error			$A_e$		< ±0.25		dB	D
4.6	Noise floor	$V_{BBI} = 2V$ , $\bar{V}_{BBI} = 3V$ $V_{BBI} = \bar{V}_{BBI} = 2.5V$		$N_{FL}$		-132 -144		dBm/Hz	D
4.7	VSWR			$VSWR_{RF}$		1.6	2		D
4.8	3rd-order baseband harmonic suppression			$S_{BBH}$	35	45		dB	D
4.9	RF harmonic suppression			$S_{RFH}$		35		dB	D
<b>5</b>	<b>Power-up Mode</b>								
5.1	Supply current	$V_{PU} \leq 0.5V$ $V_{PU} = 1V$	4, 5	$I_{PU}$		10	1	$\mu A$	D
5.2	Settling time	$C_{SPU} = 100\text{ pF}$ $C_{LO} = 100\text{ pF}$ $C_{RFo} = 1\text{ nF}$	6 to 3	$t_{sPU}$		10		$\mu s$	D
<b>6</b>	<b>Switching Voltage</b>								
6.1	Power-on		1	$V_{PUon}$	4			V	D
6.2	Power-up		1	$V_{PUdown}$			1	V	D

\*) Type means: A = 100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

- Notes:
1. The required LO level is a function of the LO frequency.
  2. In reference to an RF output level  $\leq -1\text{ dBm}$  and I/Q input level of  $400\text{ mV}_{pp}$  differential.
  3. Sideband suppression is tested without connection at pins 15 and 16. For higher requirements a potentiometer can be connected at these pins.
  4. For  $T_{amb} = -30^\circ C$  to  $+85^\circ C$  and  $V_S = 4.5V$  to  $5.5V$ .
  5. By low impedance signal source.

7. Diagrams

Figure 7-1. Typical Single Sideband Output Spectrum at  $V_S = 4.5V$  and  $V_S = 5.5V$ ,  $f_{LO} = 900\text{ MHz}$ ,  $P_{LO} = -10\text{ dBm}$ ,  $V_{BBI} = 1\text{ V}_{PP}$  (differential)  $T_{amb} = 25^\circ\text{C}$

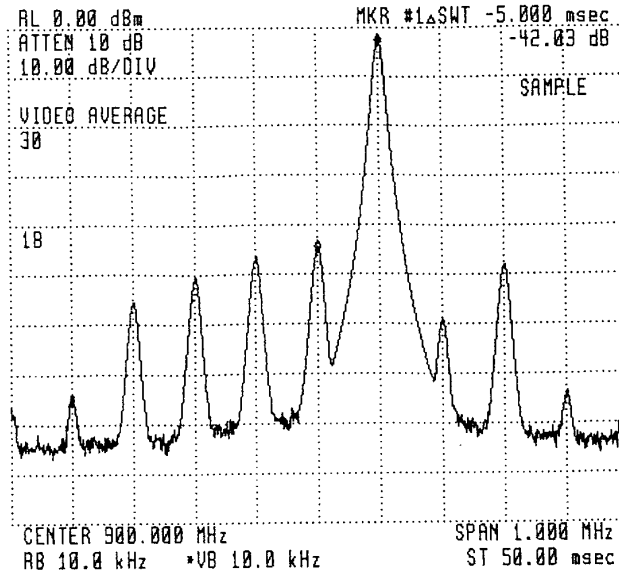


Figure 7-2. Typical GMSK Output Spectrum

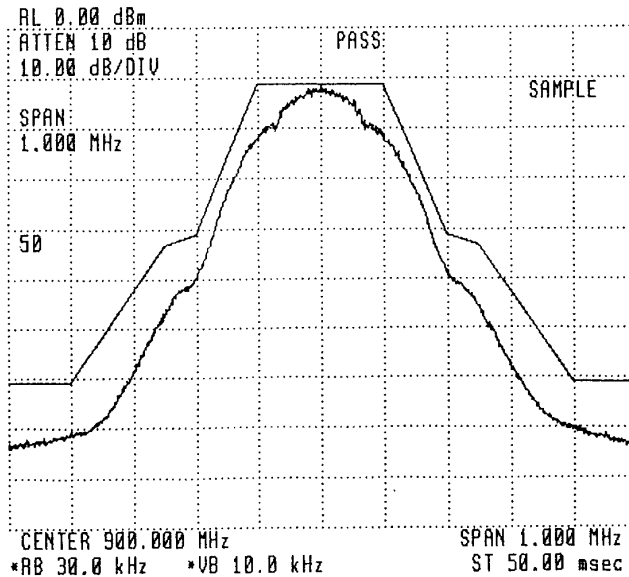


Figure 7-3. Demo Board Layout

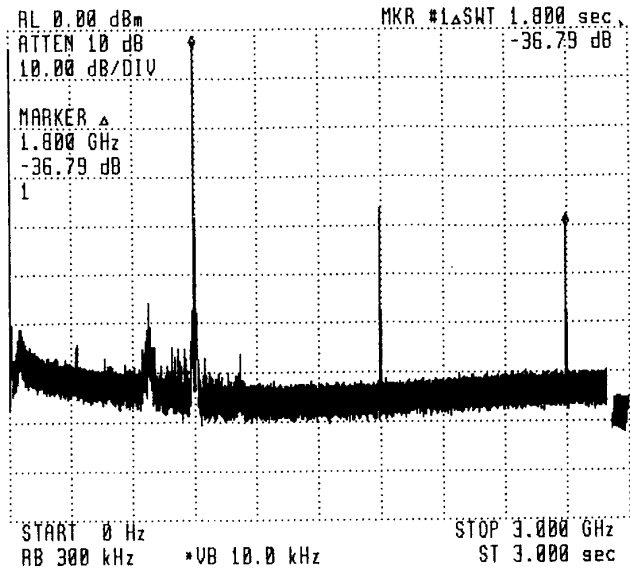


Figure 7-4. OIP3 versus  $T_{amb}$ , LO = 150 MHz, Level -20 dBm

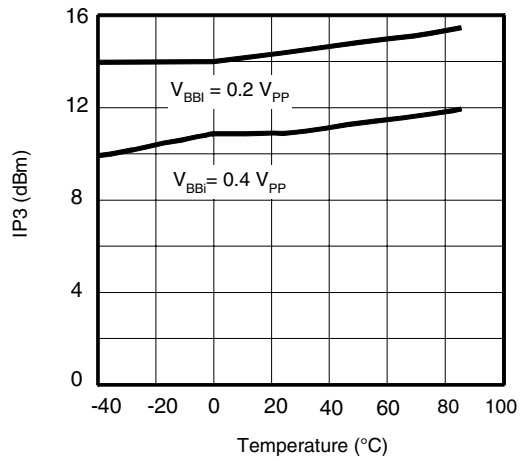


Figure 7-5. OIP3 versus  $T_{amb}$ , LO = 900 MHz, Level -10 dBm

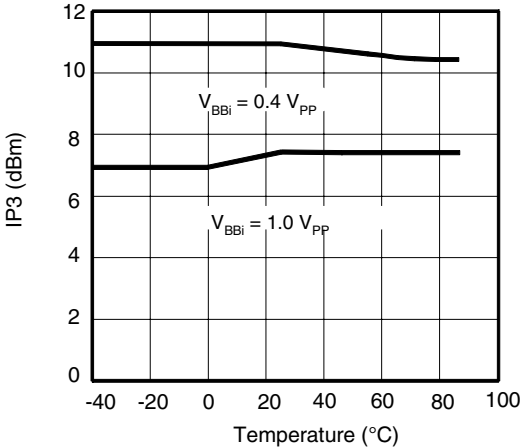


Figure 7-6. Output Power versus  $T_{amb}$

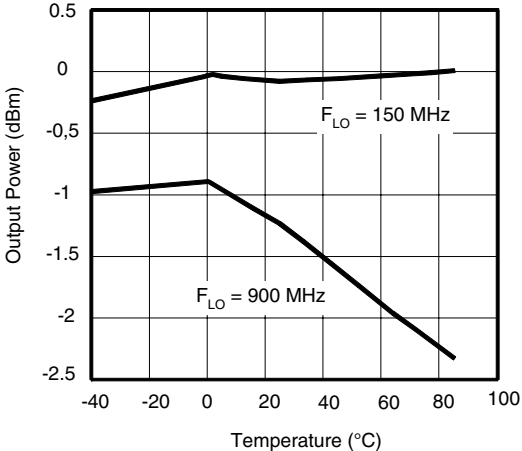
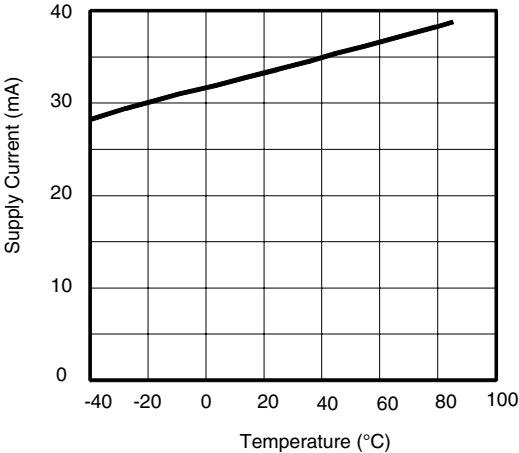
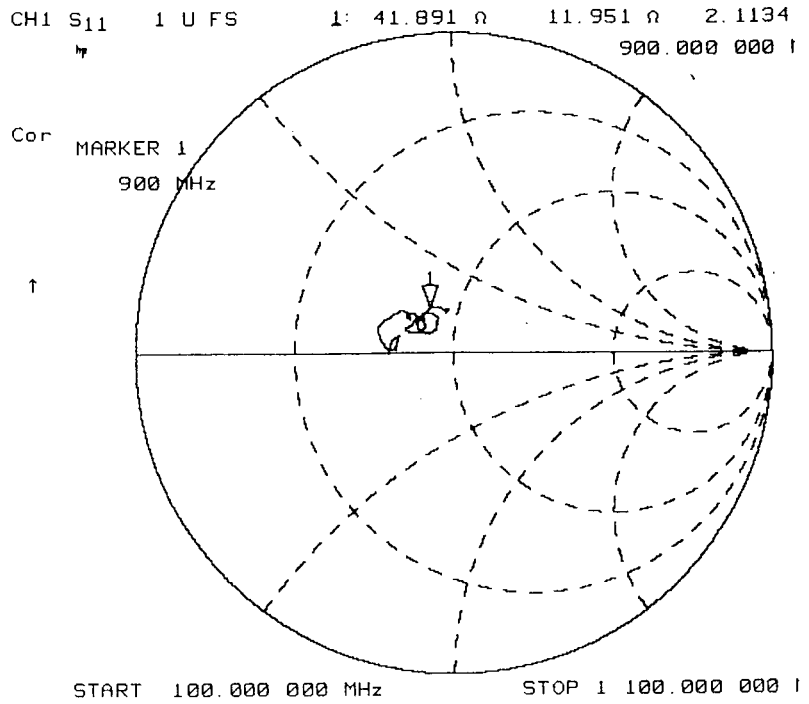


Figure 7-7. Supply Current versus  $T_{amb}$



**Figure 7-8.** Typical S11 Frequency Response of the RF Output



**Figure 7-9.** Typical VSWR Frequency Response of the RF Output

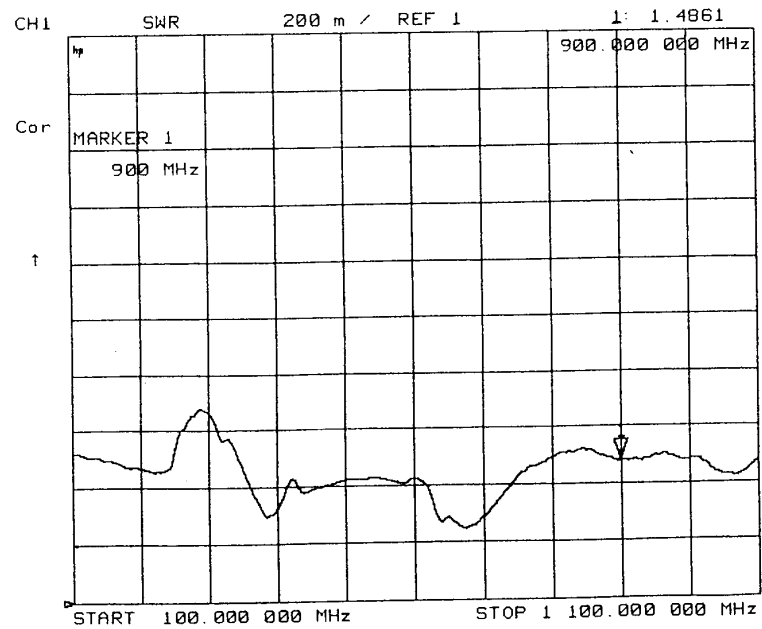




Figure 7-10. Typical S11 Frequency Response of the LO Input

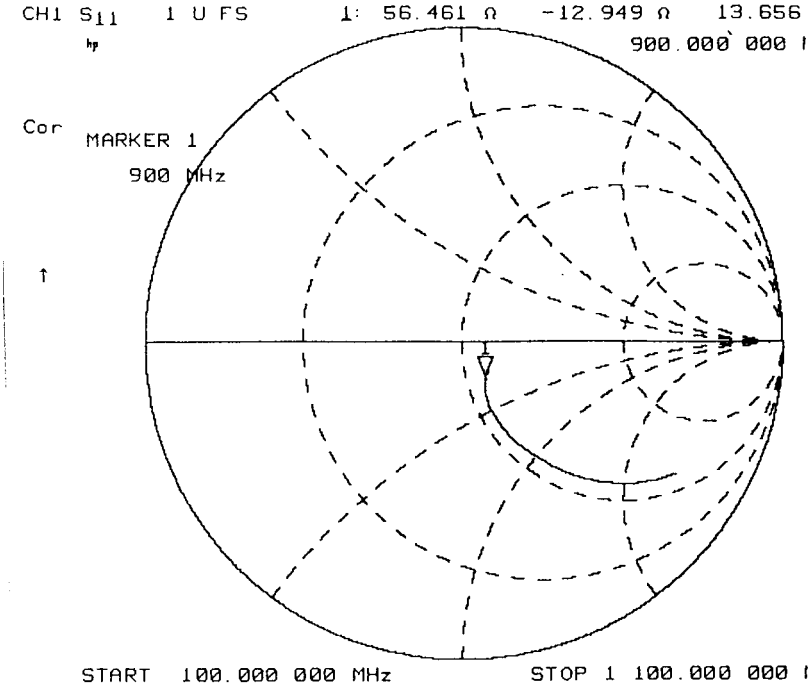
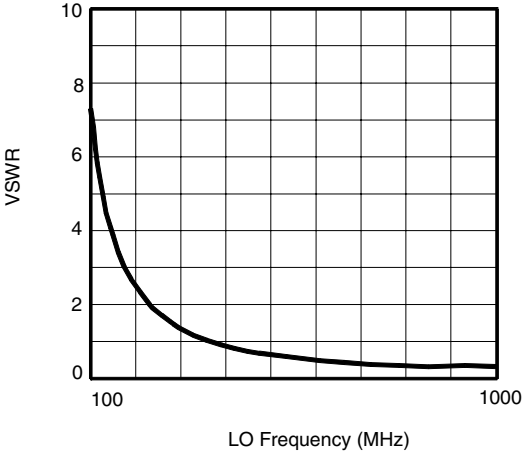
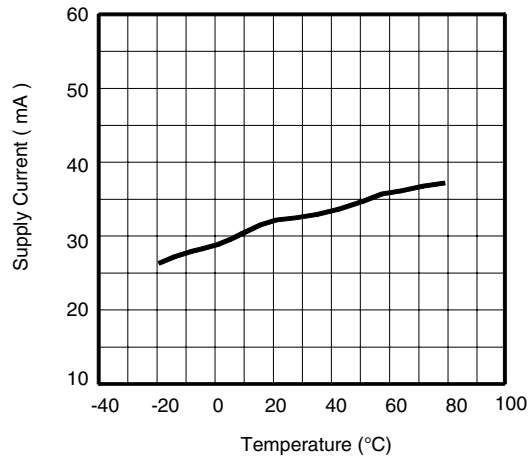


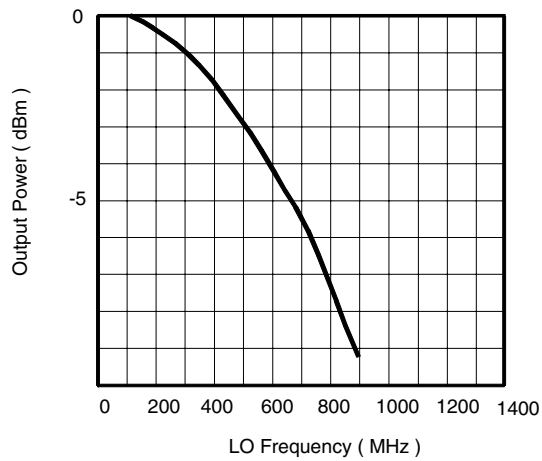
Figure 7-11. Typical VSWR Frequency Response of the LO input



**Figure 7-12.** Typical Supply Current versus Temperature at  $V_S = 5V$



**Figure 7-13.** Typical Output Power versus LO-Frequency at  $T_{amb} = 25^\circ C$ ,  $V_{BBI} = 230\text{ mV}_{PP}$  (differential)



**Figure 7-14.** Typical required  $V_{BBI}$  Input Signal (differential) versus LO Frequency for  $P_O = 0\text{ dBm}$  and  $P_{O} = -2\text{ dBm}$

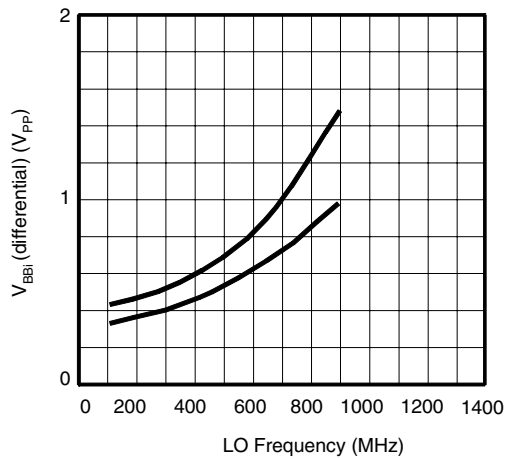


Figure 7-15. Typical useful LO Power Range versus LO Frequency at  $T_{amb} = 25^{\circ}C$

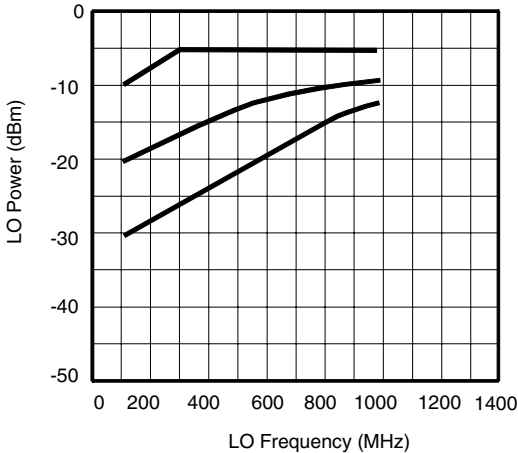


Figure 7-16. Application Circuit

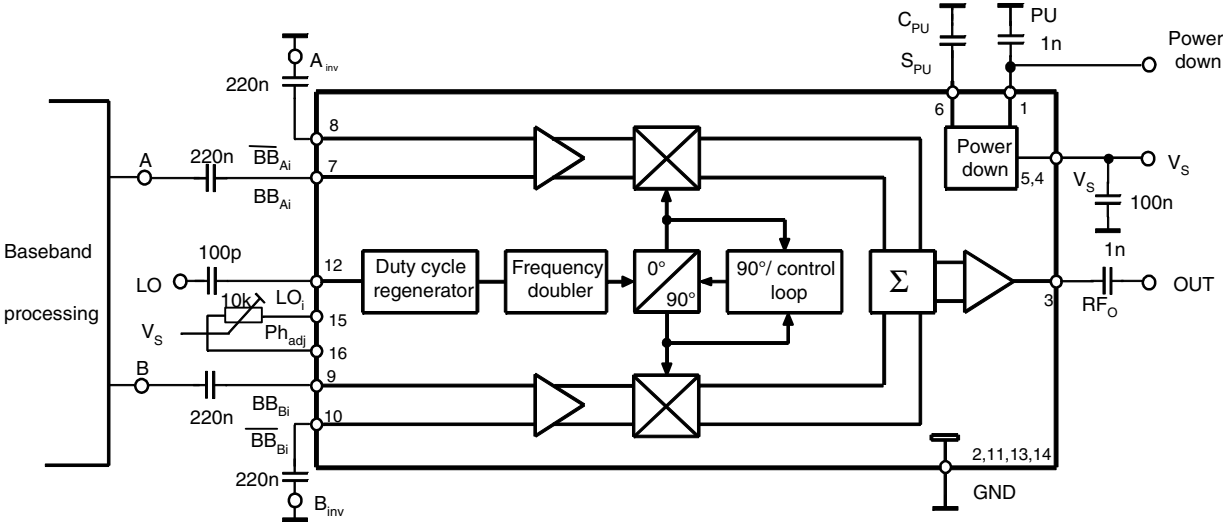
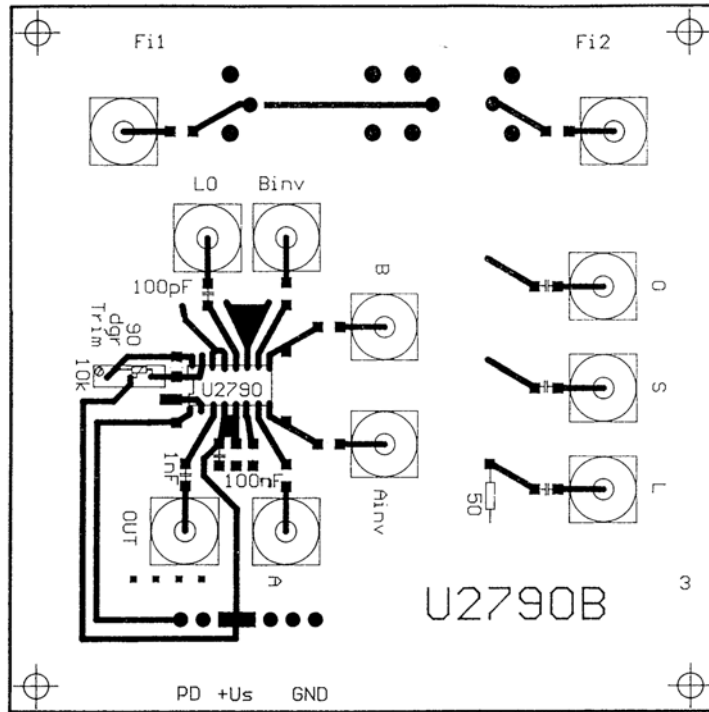


Figure 7-17. Demo Board Layout



## 8. Application Notes

### 8.1 Noise Floor and Settling Time

In order to reduce noise on the power-up control input and improve the wide-off noise floor of the 900-MHz RF output signal, capacitor  $C_{PU}$  should be connected from pin 6 to ground in the shortest possible way.

The settling time has to be considered for the system under design. For GSM applications, a value of  $C_{PU} = 1 \text{ nF}$  defines a settling time,  $t_{sPU}$ , equal or less than 3 ms. This capacitance does not have any influence on the noise floor within the relevant GSM mask. For mobile applications the mask requirements can be achieved very easily without  $C_{PU}$ .

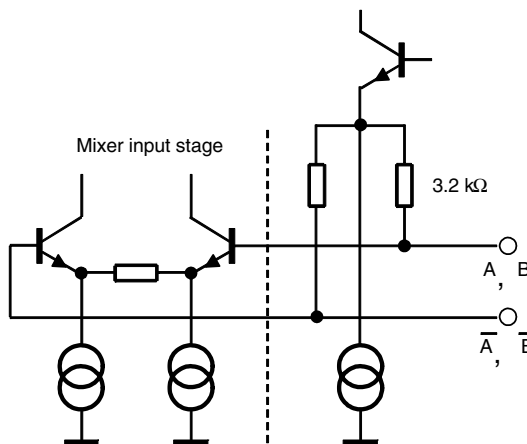
A significant improvement of the wide-off noise floor is obtainable with  $C_{PU}$  greater than 100 nF. Such values are recommended for applications where the settling time is not critical such as in base stations. Coupling capacitors for  $LO_i$  and  $RF_o$  also have a certain impact on the settling time. The values used for the measurements are  $C_{LO_i} = 100 \text{ pF}$  and  $C_{RF_o} = 1 \text{ nF}$ .

### 8.2 Baseband Coupling

The U2790B-FP (SO16) has an integrated biasing network which allows AC coupling of the baseband signal at a low count of external components. The bias voltage is  $2.5V \pm 0.15V$ .

Figure 7-17 shows the baseband input circuitry with a resistance of  $3.2 \text{ k}\Omega$  for each asymmetric input. The internal DC offset between A and A, and B and B is typically  $< \pm 1 \text{ mV}$  with a maximum of  $\pm 3 \text{ mV}$ . DC coupling is also possible with an external DC voltage of  $2.5 \pm 0.15V$ .

Figure 8-1. Baseband Input Circuitry



RF Output Circuitry LO Input Circuitry

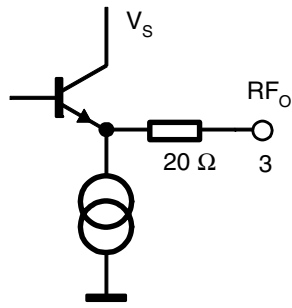
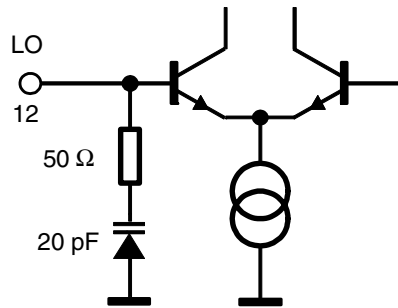


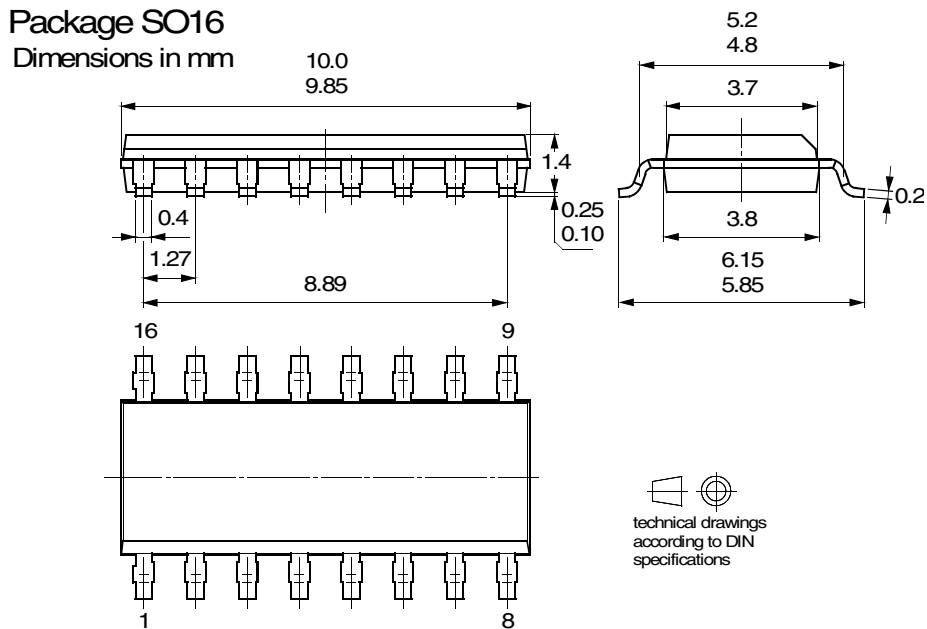
Figure 8-2. LO Input Circuitry



### 9. Ordering Information

Extended Type Number	Package	Remarks
U2790B-NFPH	SO16	Tube, Pb-free
U2790B-NFPG3H	SO16	Taped and reeled, Pb-free

### 10. Package Information



### 11. Revision History

Please note that the following page numbers referred to in this section refer to the specific revision mentioned, not to this document.

Revision No.	History
4583D-CELL-07/06	<ul style="list-style-type: none"> <li>• Page 3, Abs. Max.Ratings table: Storage temperature values changed</li> <li>• Page 2, Pin Description table: symbol of Pins 8 and 10 changed</li> <li>• Put datasheet in a new template</li> </ul>



## Atmel Corporation

2325 Orchard Parkway  
San Jose, CA 95131, USA  
Tel: 1(408) 441-0311  
Fax: 1(408) 487-2600

## Regional Headquarters

### Europe

Atmel Sarl  
Route des Arsenaux 41  
Case Postale 80  
CH-1705 Fribourg  
Switzerland  
Tel: (41) 26-426-5555  
Fax: (41) 26-426-5500

### Asia

Room 1219  
Chinachem Golden Plaza  
77 Mody Road Tsimshatsui  
East Kowloon  
Hong Kong  
Tel: (852) 2721-9778  
Fax: (852) 2722-1369

### Japan

9F, Tonetsu Shinkawa Bldg.  
1-24-8 Shinkawa  
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Japan  
Tel: (81) 3-3523-3551  
Fax: (81) 3-3523-7581

## Atmel Operations

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2325 Orchard Parkway  
San Jose, CA 95131, USA  
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Maxwell Building  
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Fax: (44) 1355-242-743

### RF/Automotive

Theresienstrasse 2  
Postfach 3535  
74025 Heilbronn, Germany  
Tel: (49) 71-31-67-0  
Fax: (49) 71-31-67-2340

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Colorado Springs, CO 80906, USA  
Tel: 1(719) 576-3300  
Fax: 1(719) 540-1759

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38521 Saint-Egreve Cedex, France  
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